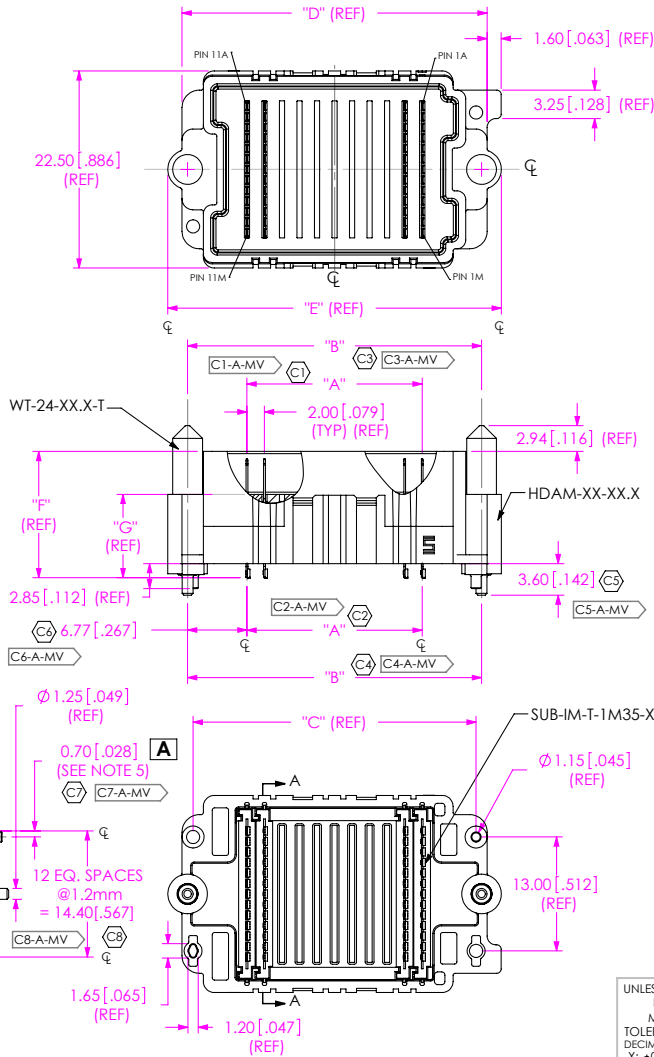


REVISION A

DO NOT
SCALE FROM
THIS PRINT



HDAM-XX-XX.X-X-13-X-X

No. OF POSITIONS
(13 ROW PER POSITION)
-11
-15
-23

LEAD STYLE
-12.0: 12MM
-17.0: 17MM

PLATING SPECIFICATION

-S: SELECTIVE, .000030 INCHES GOLD IN MATING AREA,
MATTE TIN ON TAIL AND GUIDE PINS

OPTION

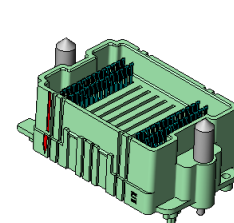
-P: PICK & PLACE PAD
(USE MPP-26-01-N)
SOLDER CHARGE MATERIAL
-1: 63%TIN / 37% LEAD
-2: 95.5% TIN / 3.8% SILVER
0.7% COPPER (LEAD FREE)

No. OF ROWS
-13

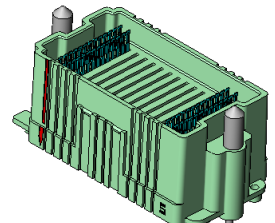
STYLE	"BODY CALLOUT"	"TERMINAL WAFER"	"GUIDE PIN"
-12.0	HDAM-XX-12.0	SUB-IM-T-1M35-12.0-S-X	WT-24-12.0-T
-17.0	HDAM-XX-17.0	SUB-IM-T-1M35-17.0-S-X	WT-24-17.0-T

TABLE 2 STACK HEIGHT		
HDAM LEAD STYLE	HDAF LEAD STYLE	
-12.0	20.0MM	30.0MM
-17.0	25.0MM	35.0MM

TABLE 3								
No. OF POS	LEAD STYLE	"A"	"B"	"C"	"D"	"E"	"F"	"G"
11	12.0	20.0 [1.787]	33.55 [1.321]	32.30 [1.272]	34.82 [1.371]	38.06 [1.498]	14.41 [1.567]	9.51 [1.374]
15	12.0	28.0 [1.102]	41.55 [1.636]	40.30 [1.587]	42.82 [1.686]	46.06 [1.813]	14.41 [1.567]	9.51 [1.374]
23	12.0	44.0 [1.732]	57.55 [2.266]	56.30 [2.217]	58.82 [2.316]	62.06 [2.493]	14.41 [1.567]	9.51 [1.374]
11	17.0	20.0 [1.787]	33.55 [1.321]	32.30 [1.272]	34.82 [1.371]	38.06 [1.498]	19.41 [1.764]	14.51 [1.571]
15	17.0	28.0 [1.102]	41.55 [1.636]	40.30 [1.587]	42.82 [1.686]	46.06 [1.813]	19.41 [1.764]	14.51 [1.571]
23	17.0	44.0 [1.732]	57.55 [2.266]	56.30 [2.217]	58.82 [2.316]	62.06 [2.493]	19.41 [1.764]	14.51 [1.571]



(-12.0 SHOWN)



(-17.0 SHOWN)

UNLESS OTHERWISE SPECIFIED,
DIMENSIONS ARE IN
MILLIMETERS [INCHES].
TOLERANCES ARE:
DECIMALS ANGLES
.X: ±0.3 [.01]
.XX: ±0.13 [.005]
.XXX: ±0.051 [.0020]

MATERIAL: DO NOT SCALE DRAWING
INSULATOR: LCP, COLOR: BLACK
CONTACT: COPPER ALLOY
WAFER MATERIAL: LCP, COLOR: BLACK
GUIDE PIN MATERIAL: BRASS
PICK AND PLACE PAD: COPPER ALLOY

PROPRIETARY NOTE
THIS DOCUMENT CONTAINS INFORMATION
CONFIDENTIAL AND PROPRIETARY TO
SAMTEC, INC. AND SHALL NOT BE REPRODUCED
OR TRANSFERRED TO OTHER DOCUMENTS OR
DISCLOSED TO OTHERS OR USED FOR ANY
PURPOSE OTHER THAN THAT WHICH IT WAS
OBTAINED WITHOUT THE EXPRESSED WRITTEN
CONSENT OF SAMTEC, INC.

SHEET SCALE: 1:5:1
SolidWorks

SAMTEC
520 PARK EAST BLVD. NEW ALBANY, IN 47150
* PHONE: 812.944.6733 FAX: 812.948.5047
e-Mail: INFO@SAMTEC.COM CODE: 55322

DESCRIPTION:
2.0MM PITCH HD ARRAY TERMINAL ASSEMBLY

DWG. NO.
HDAM-XX-XX.X-X-13-X-X
BY: D KNOWLDEN 7/15/2005 SHEET 1 OF 2

NOTES:

1. C REPRESENTS A CRITICAL DIMENSION.
2. MINIMUM PUSHOUT FORCE: 2.22N [5 LB], FOR WAFERS
3. CONNECTORS TO BE PACKAGED IN TRAYS.
4. USE THESE SURFACES TO MEASURE "G" DIMENSION.
5. DIMENSION FROM C OF END TAIL TO C OF A PIN.

FIG. 1
-11: IT POSITION
(HDAM-11-12.0-X-13-X-X SHOWN)
(SOME WAFERS NOT SHOWN FOR CLARITY)

**DESIGNED & DIMENSIONED IN MILLIMETERS
(INCHES FOR REFERENCE ONLY)**

REVISION A

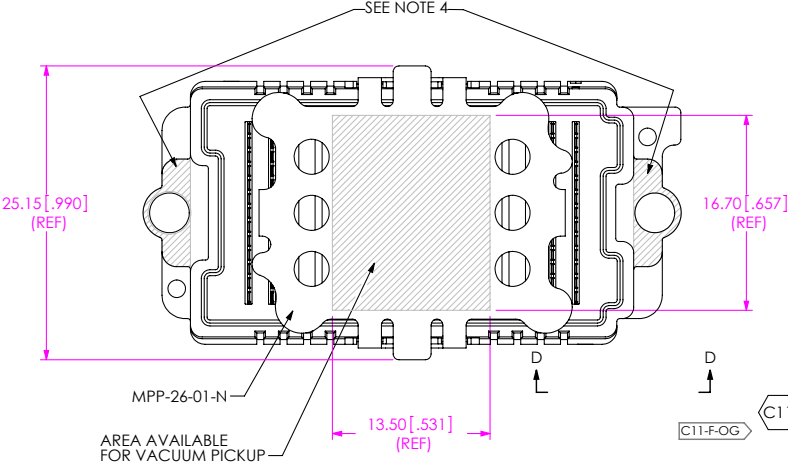
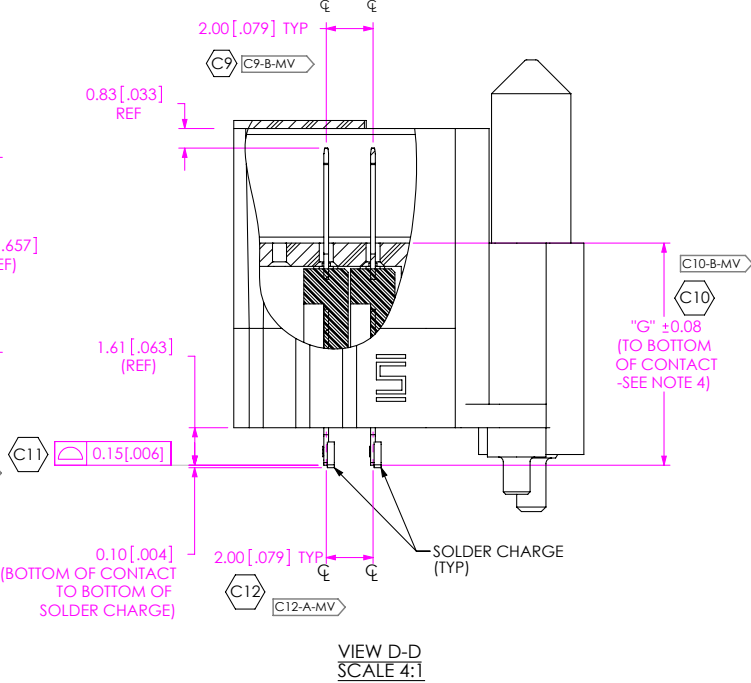
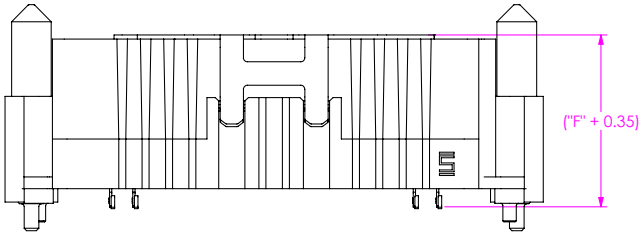


FIG. 2
-15: T5 POSITION
(HDAM-15-12.0-X-13-X-P SHOWN)
(SOME WAFERS NOT SHOWN FOR CLARITY)



CRITICAL DIMENSION INSPECTION INSTRUCTION TABLE		
ASSEMBLY OPERATION	START-UP INSPECTION INSPECT CODE A	IN-PROCESS INSPECTION INSPECT CODE B
FILL WAFERS	C1, C2, C7, C8, C12	C9, C10
FILL WELD TABS	C2, C3, C4, C5, C6, C12	C10
INSTALL PAD	C2, C6, C12	N/A

F:\DWG\MISC\MKTG\HDAM-XX-XX-X-13-X-X-MKT.SLDRW

PROPRIETARY NOTE THIS DOCUMENT CONTAINS INFORMATION CONFIDENTIAL AND PROPRIETARY TO SAMTEC, INC. AND SHALL NOT BE REPRODUCED OR TRANSFERRED TO OTHER DOCUMENTS OR DISCLOSED TO OTHERS OR USED FOR ANY PURPOSE OTHER THAN THAT WHICH IT WAS OBTAINED WITHOUT THE EXPRESSED WRITTEN CONSENT OF SAMTEC, INC. DO NOT SCALE DRAWING SHEET SCALE: 2:1	SAMTEC 520 PARK EAST BLVD, NEW ALBANY, IN 47150 * PHONE: 812.944.6733 FAX: 812.948.5047 e-Mail: INFO@SAMTEC.COM CODE: 55322	
	DESCRIPTION:	2.0MM PITCH HD ARRAY TERMINAL ASSEMBLY
	DWG. NO.	HDAM-XX-XX.X-X-13-X-X
	BY:D KNOWLDEN	7/15/2005 SHEET 2 OF 2